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FCI Introduces XCede® Backplane Connector Products

FCI, a leading manufacturer of connectors and interconnect systems, announces the release of XCede® vertical backplane headers and right-angle daughter card receptacles designed for 25 Gb/s performance. Vertical backplane header configurations provide two, four or six differential signal pairs per column wafer with four, six or eight wafers per signal connector module. The vertical header range also includes options with two-wall, three-wall, or four-wall connector shrouds. Among the three-wall options are versions with integrated guide posts and polarization key openings.

FCI is licensed second source to Amphenol which allows FCI to manufacture, market, and sell all XCede products and extensions.

"As evidence of both companies' commitment to second-source partnering, FCI and Amphenol have successfully concluded extensive inter-mateability qualification testing of their respective 4-pair XCede header and receptacle products to assure acceptable performance regardless of how backplane headers or daughter card connectors are interchanged by a customer," said Nicholas Tan, FCI Global Product Marketing Manager.

The XCede connector platform provides a clear long-term migration path for customers who are designing equipment platforms that will need to evolve to enable higher speed signaling and higher levels of performance in future years. The use of advanced engineering polymers in a resonance-damping shield eliminates crosstalk resonances and enables very low crosstalk across a wide frequency range.

XCede connectors also address requirements for higher linear signal density at the backplane or midplane interface. Connectors with six differential pairs per column fit 36 mm minimum card slot pitch and provide 82.4 differential signal pairs/inch. Four-pair connectors provide 54.9 signal pairs/inch and can be used down to 25 mm card slot pitch. Two-pair connectors fit on as little as 15 mm slot pitch and support 27.5 signal pairs/inch along the card edge.

Complementary guidance and power modules are also included in the product range. In addition to providing individual right-angle receptacle signal modules, customized groupings of right-angle signal, guidance and power modules can be attached to a single wafer organizer to form an integrated daughter card connector.

Press release



XCede backplane headers also provide the ruggedness and long-term reliability required in today's high-end systems. The wide ground contacts in the vertical header feature a stiffening rib that extends near the tip of the contact and are advanced well ahead of the signals for exceptional robustness and signal pin protection.

For more information about XCede high-speed connectors, visit FCI on the web at www.fciconnect.com/highspeed.

XCede® is a registered trademark of Amphenol Corporation

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About FCI

With operations in 30 countries and sales of 1.28 billion euros in 2010, FCI is a leading manufacturer of connectors. Our 14,000 employees are committed to providing customers with high-quality, innovative products for a wide range of consumer and industrial applications.

For more information: www.fci.com